



EVG®850 NanoCleave™ Layer Release System – February 6, 2024



Newsletter: 6th February 2024



NANOCLEAVE™ LAYER TRANSFER REVOLUTIONIZES 3D / ADVANCED PACKAGING AND LOGIC SCALING

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FEATURED



The complexities of onshoring chip production amidst geopolitical risks

Recent developments, including the Covid-19 pandemic and catastrophic events like freezes and fires, have shed light on the disruptions caused by chip shortages and related supply chain issues. Moreover, the uncertainty created by rising geopolitical tensions has awakened the sector to impacts that exceed the balance sheet of any one firm. By George Haitzsch, who leads the North American Tech + Media + Telecom Division for WTW.

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## INDUSTRY NEWS

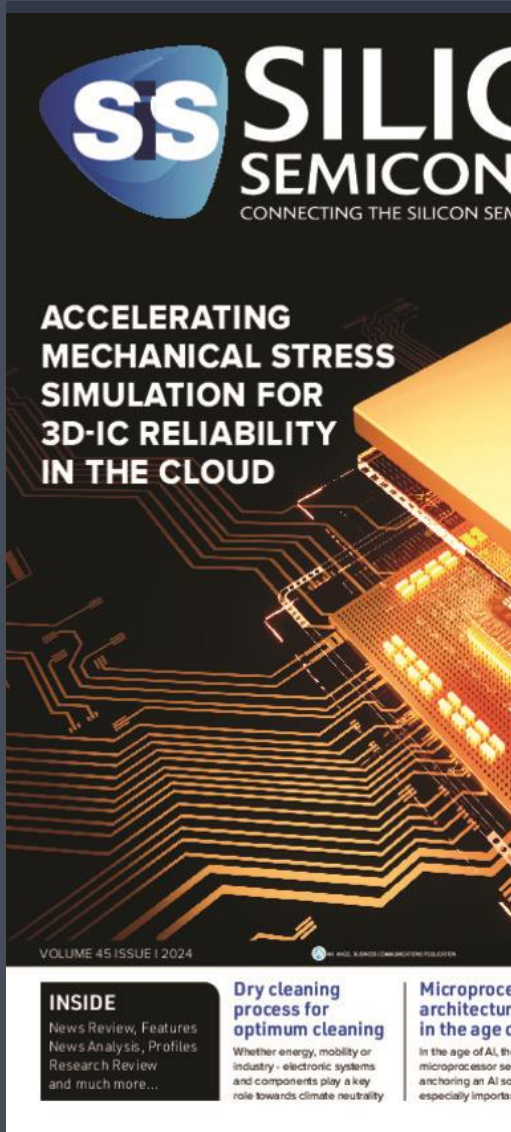
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## COMPANY NEWS

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- [Nordic Semiconductor and Arm reaffirm partnership](#)
- [Infineon and Honda enter strategic collaboration](#)
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### Filling the metrology void

Nearfield Instruments B.V. recently launched AUDIRA – said to be the industry’s first and only in-line, non-destructive subsurface metrology system for advanced semiconductor manufacturing. By Niranjan Saikumar; Co-authors: Nelda Antonovaitė, Irene Battisti, Taras Piskunov, Mehdi Soozande

### INTERVIEWS

- [Volkswagen Group reorganises semiconductor procurement strategy](#)
- [All roads lead to Arizona](#)

- [Time to celebrate and accelerate diversity, equity and inclusion](#)
- [The potential of AI](#)

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## LAB NEWS

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- [Imec expands its US presence](#)
- [CEA-Leti develops 'cost-saving' CMOS-compatible 200mm process technology](#)
- [CEA-Leti reports 'breakthrough' 3D Sequential Integration \(3DSI\)](#)

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## A layer transfer technology revolution



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EVG's Heterogeneous Integration and NILPhotonics® Competence Centers provide an open access innovation incubator for customers and partners across the microelectronics supply chain.

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**AngelTech 2024 • 16th - 17th April 2024 • Brussels, Belgium**

Comprising of CS International (celebrating its 13th anniversary), PIC International (now in its 8th year), and Power Electronics (PE) International (now in its 2nd year).



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